



SISPAD 2007

International Conference on
Simulation of Semiconductor Processes and Devices

Call for Papers

The 12th International Conference on Simulation of Semiconductor Devices and Processes (SISPAD) will be held from September 25-27, 2007 at the TU Wien, Vienna, Austria. Following the tradition of the SISPAD conference series as the leading forum for Technology Computer-Aided Design (TCAD), this conference provides an opportunity for the presentation and discussion of recent advances in modeling and simulation of semiconductor devices, processes and equipment. The scientific program consists of invited and contributed presentations and a poster session.



Conference Chairmen

T. Grasser, Austria
S. Selberherr, Austria

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General Topic Areas

Device simulation, including transport in nano-structures
Models of VLSI device scaling limits, quantum effects, and novel devices
Process simulation, including both continuum and atomistic approaches
Equipment, topography, and lithography simulation
Interconnect modeling and algorithms including noise and parasitic effects
Compact device modeling for circuit simulation
Integration of circuit and device simulation
User interfaces and visualization
High performance computing, numerical methods and algorithms
Mesh generation and adaptation
Simulation of devices like microsensors and optoelectronic devices
Benchmarking, calibration, and verification of simulators

Abstracts and Proceedings

A two page abstract should be uploaded to the conference homepage. Postal submission of hardcopies is not acceptable. Authors of accepted papers are request to submit a four page final paper which will be published in the conference proceedings. Additional information for authors is available on the webpage www.sispad.org

Important Dates

Abstract submission:	March 2, 2007
Notification of acceptance:	May 4, 2007
Camera ready copy:	May 25, 2007
Conference:	September 25-27, 2007

Venue

The conference will be held in the Electrical Engineering building of the TU Wien: Gusshausstrasse 27-29, A-1040 Vienna, Austria

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